mail

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

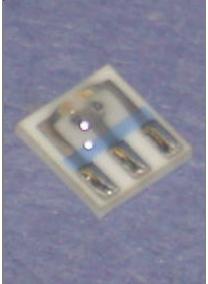


Contact us

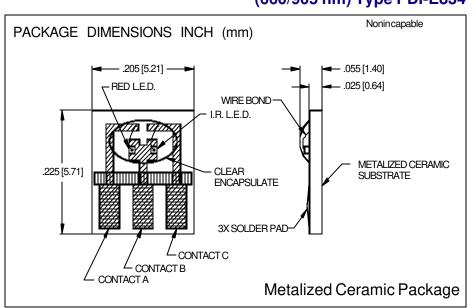
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



PHOTONIC <u>DETECTORS INC</u>.



Three Drive Emitter, Oximeter Component (660/905 nm) Type PDI-E834



FEATURES

- Low cost
- 660 nm +/- 3 nm
- 3 drive line

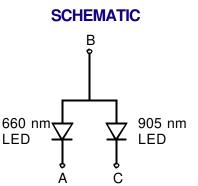
DESCRIPTION: The **PDI-E834** is a three drive line dual emitter oximeter component. The 660 and 905 nm GaAlAs emitters are high power LPE grown. The metalized ceramic has clear epoxy encapsulation with top side solder pads. These components are ideal for O.E.M. and repair replacements of oximeter probe assemblies.

APPLICATIONS

- Oximeter probes
- Finger clamps
- Reusable probes

ABSOLUTE MAXIMUM RATING (TA=25°C unless otherwise noted)

SYMBOL	PARAMETER	MIN	MAX	UNITS					
Pd	Power Dissipation I _F =20 mA		250	mW					
ا _۳	Continuous Forward Current		30	mA					
FP	Peak Forward Current		200	mA					
VR	Reverse Voltage		4	V					
T₀&Ts	Storage & Operating Temp	-40	+80	۰C					
TS	Soldering Temperature*		240	°C					
* For 3 soconds may using a boat sink									



* For 3 seconds max using a heat sink.

ELECTRO-OPTICAL CHARACTERISTICS (TA=25°C unless otherwise noted)

SYMBOL	CHARACTERISTIC	TESTCONDITIONS	660 nm		905 nm				
			MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Po	Radiant Flux**	l _F = 20 mA	1.8	2.4		1.2	1.8		mW
Ιv	Luminous Intensity**	l _F = 20 mA	20	30					mcd
VF	Forward Voltage	l _F = 20 mA		1.8	2.4		1.2	1.5	V
V _R	Reverse breakdown	I _F = 10 µµA	5			5			V
λ_{p}	Peak Wavelength	l _F = 20 mA	658	661	664	895	905	915	nm
Δλ	Spectral Bandwidth	l _F = 20 mA		25			50		nm
T _r	Rise Time	l _F = 20 mA		0.8			0.8		μS
Tr	Fall Time	l _F = 20 mA		0.8			0.8		μS

** Bare chip measured packaged in a flat TO-18/TO-46 header without resin coating or cap.

Information in this technical data sheet is believed to be correct and reliable. However, no responsibility is assumed for possible inaccuracies or omission. Specifications are subject to change without notice. [FORM NO. 100-PDI-E834 REV A]